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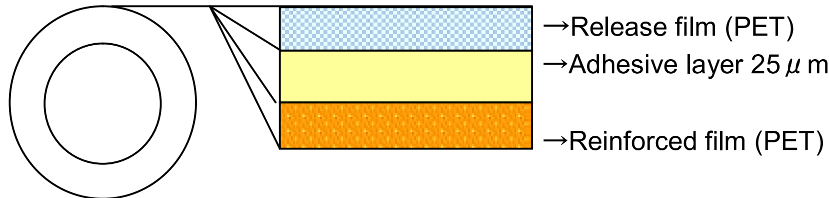
TOYOCHEM

TECHNICAL DATA SHEET

LIOELM TSU™550

This LowDk bonding sheet is designed for high-speed transmission circuit. TSU550 has excellent solder heat resistance / excellent dielectric characteristics / excellent adhesive strength / excellent workability.
TSU550 is low Dk adhesive sheet for next generation high-speed transmission devices. Our product offers transmission loss decrease.

【Structure】



【Properties】

			Unit	TSU550
Adhesive layer			μm	25
Reinforced film (PET)			μm	50
Release film (PET)			μm	50
Dk 28GHz				2.77
Df 28GHz				0.0020
Adhesive Strength	TO CU	Before reflow	N/10cm	More than 5
		After reflow		More than 5
Solder reflow（Peak 260℃）			—	Pass

※ Above data is our self-conducted test result but not our guaranteed performance.

【Peel strength measurement conditions】

1. Structure: LCP CCL or、M-PI CCL / CU/TSU / CU/ LCP CCL or、M-PI CCL
2. Laminating conditions: Laminate 90℃→Press 180℃-2MPa-60min
3. Peel speed : 50mm/min
4. Peel angle: 90°

【Press conditions】

Laminating condition: Laminate 90℃ 0.3 MPa 1M/㎜
Press condition: 180℃x2-3MPa 60min or 180℃x2-3MPax3min vacuum quick press + Post cure 180℃x1Hr

【Notice of Storage Condition】

・ TSU550 should be stored under 10℃ / 70%RH.
・ After taking out from the refrigerated environment above, please place TSU550 in a room temperature environment before use.
・ Recommended restoration time is more than 7 hours
・ If it takes time before hot pressing, it is recommended to store back in a refrigerated environment

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